Thyristors logic level

BT169 series

GENERAL DESCRIPTION

Passivated, sensitive gate thyristors in a plastic envelope, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

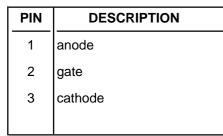
PINNING - TO92 variant

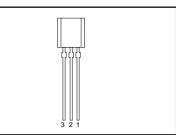
QUICK REFERENCE DATA

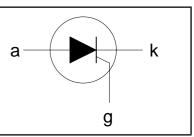
SYMBOL	PARAMETER	MAX	MAX	MAX	MAX	UNIT
	BT169	•	•	•	•	
V _{DRM} ,	Repetitive peak	В	D	Е	G	V
V _{RRM}	off-state voltages Average on-state	200	400	500	600	А
T(AV)	current RMS on-state current	0.5	0.5	0.5	0.5	A
T(RMS) T _{TSM}	Non-repetitive peak on-state current	0.8 8	0.8 8	0.8 8	0.8 8	Â

PIN CONFIGURATION

SYMBOL







LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT		
V _{drm} , V _{rrm}	Repetitive peak off-state voltages		-	B 200 ¹	D 400 ¹	E 500 ¹	G 600 ¹	V
I _{T(AV)}	Average on-state current	half sine wave; T _{lead} ≤ 83 °C	-		0	.5		A
T(RMS)	RMS on-state current	all conduction angles	-			.8		A
ITSM	Non-repetitive peak on-state current	t = 10 ms t = 8.3 ms half sine wave; T _i = 25 °C prior to surge	-			9		A A
l²t dl _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after triggering	t = 10 ms $I_{TM} = 2 \text{ A}; I_G = 10 \text{ mA};$ $dI_G/dt = 100 \text{ mA/}\mu\text{s}$	-			32 0		A²s A/µs
I _{GM} V _{GM} V _{RGM} P _{GM}	Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power		- - -			1		A V V W
P _{G(AV)} T _{stg} T _j	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- -40 -			.1 50 25		°℃ ℃

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-lead}	Thermal resistance junction to lead		-	-	60	K/W
R _{th j-a}	Thermal resistance junction to ambient	pcb mounted; lead length = 4mm	-	150	-	K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_{D} = 12 \text{ V}; I_{T} = 10 \text{ mA};$ gate open circuit	-	50	200	μA
	Latching current	$V_{D} = 12 \text{ V}; \text{ I}_{GT} = 0.5 \text{ mA}; \text{ R}_{GK} = 1 \text{ k}\Omega$	-	2	6	mA
	Holding current	$V_{D} = 12 \text{ V}; \text{ I}_{GT} = 0.5 \text{ mA}; \text{ R}_{GK} = 1 \text{ k}\Omega$	-	2	5	mA
V _T	On-state voltage	$I_T = 1 A$	-	1.2	1.35	V
V _{GT}	Gate trigger voltage	\dot{V}_{D} = 12 V; I _T = 10 mA; gate open circuit	-	0.5	0.8	V
		$V_{D} = V_{DRM(max)}$; $I_{T} = 10 \text{ mA}$; $T_{j} = 125 \text{ °C}$;	0.2	0.3	-	V
		gate open circuit				
I _D , I _R	Off-state leakage current	$\breve{V}_{D} = V_{DRM(max)}; V_{R} = V_{RRM(max)}; T_{j} = 125 \text{ °C};$	-	0.05	0.1	mA
		$R_{GK} = 1 k\Omega$				

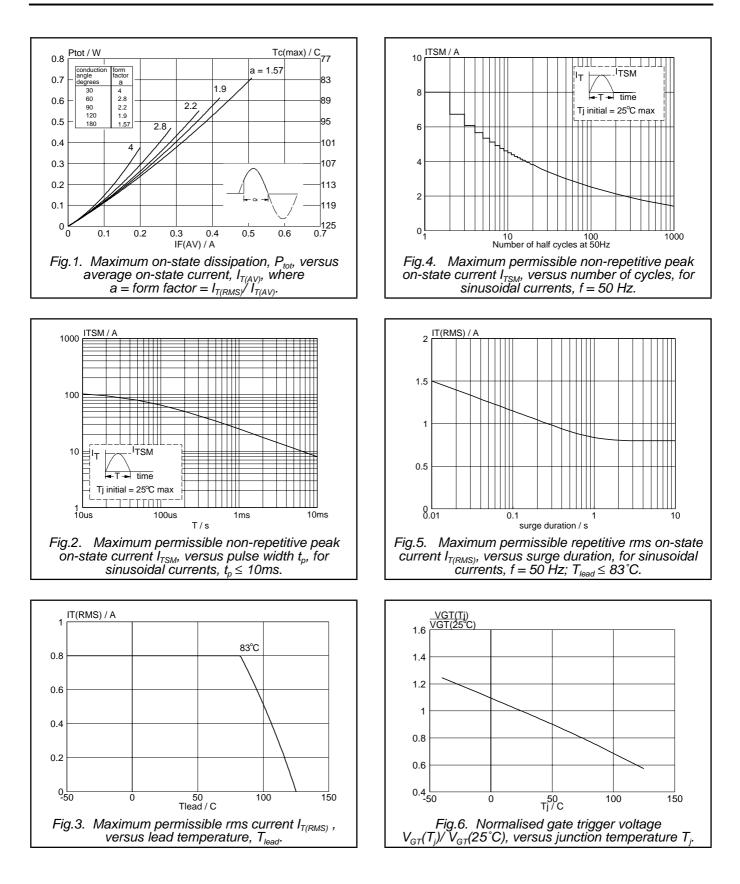
DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform; $R_{GK} = 1 k\Omega$	500	800	-	V/µs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 2 \text{ A}; V_D = V_{DRM(max)}; I_G = 10 \text{ mA};$ $dI_C/dt = 0.1 \text{ A/us}$	-	2	-	μs
t _q	Circuit commutated turn-off time	$V_{D}^{-} = 67\% V_{DRM(max)}^{-}$; $T_{i} = 125 °C;$ $I_{TM}^{-} = 1.6 A; V_{R}^{-} = 35 V; dI_{TM}^{-}/dt = 30 A/\mu s;$ $dV_{D}^{-}/dt = 2 V/\mu s; R_{GK}^{-} = 1 k\Omega$	-	100	-	μs

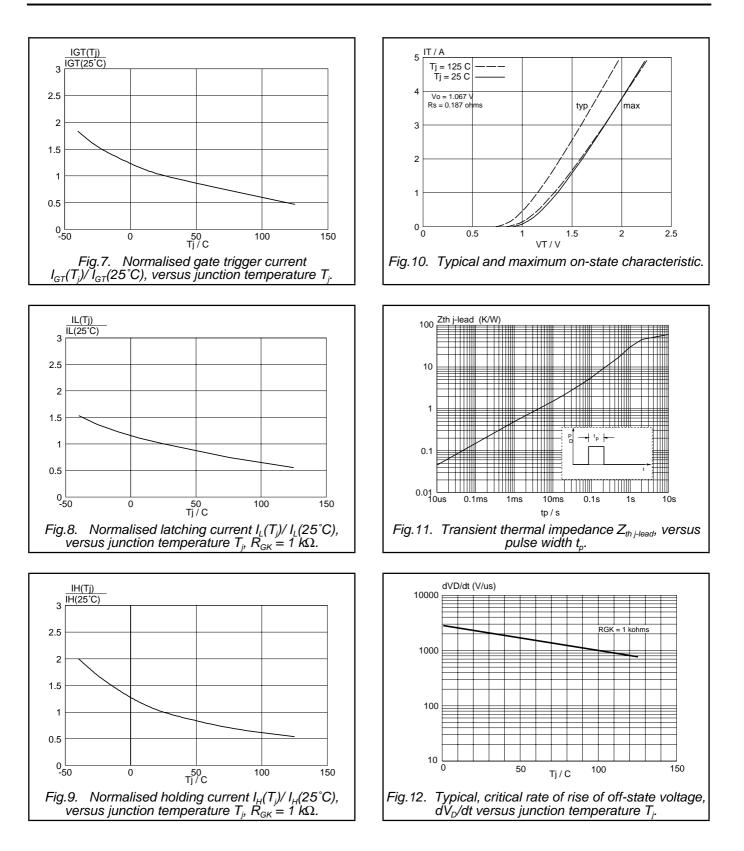
BT169 series

Thyristors logic level



BT169 series

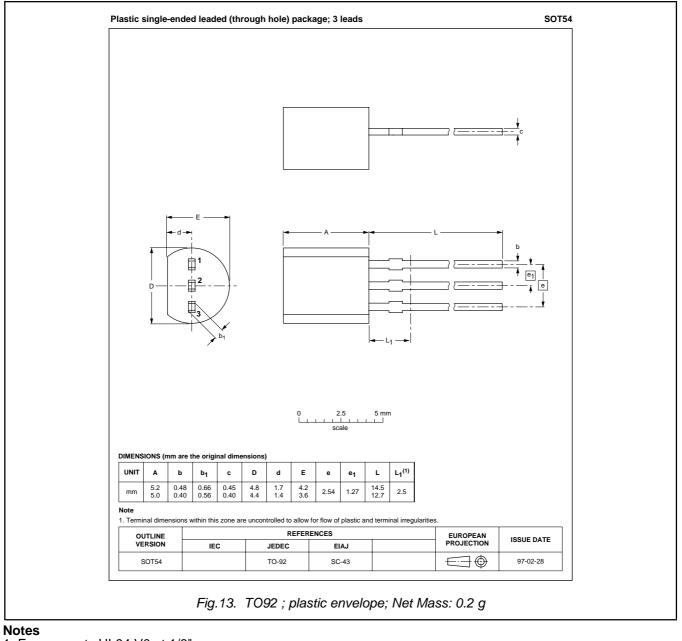
Thyristors logic level



BT169 series

Thyristors logic level

MECHANICAL DATA



1. Epoxy meets UL94 V0 at 1/8".

Thyristors logic level

BT169 series

DEFINITIONS

DATA SHEET STATUS					
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS			
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice			
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product			
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A			

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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